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November 2010

FQD3P50TM_F085

500V P-Channel MOSFET

General Description

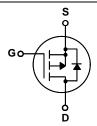
These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for electronic lamp ballast based on complimentary half bridge.

Features

- -2.1A, -500V, $R_{DS(on)}$ = 4.9 Ω @V_{GS} = -10 V Low gate charge (typical 18 nC)
- Low Crss (typical 9.5 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- Qualified to AEC Q101
- · RoHS Compliant





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQD3P50TM_F085	Units
V _{DSS}	Drain-Source Voltage		-500	V
I _D	Drain Current - Continuous (T _C = 25°C)	-2.1	Α
	- Continuous (T _C = 100°C	C)	-1.33	А
I _{DM}	Drain Current - Pulsed	(Note 1)	-8.4	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		250	mJ
I _{AR}	Avalanche Current	(Note 1)	-2.1	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		-4.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W
_	Power Dissipation (T _C = 25°C)		50	W
	- Derate above 25°C	T T	0.4	W/°C
T_J , T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-500			V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I _D = -250 μA, Referenced to 25°C		0.42		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -500 V, V _{GS} = 0 V		-	-1	μА
		V _{DS} = -400 V, T _C = 125°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -1.05 \text{ A}$		3.9	4.9	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -50 \text{ V}, I_{D} = -1.05 \text{ A} \text{ (Note 4)}$		2.1		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		510 70 9.5	90 12	pF pF
	ing Characteristics			9.5	12	рг
t _{d(on)}	Turn-On Delay Time	V _{DD} = -250 V, I _D = -2.7 A,		12	35	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		56	120	ns
t _{d(off)}	Turn-Off Delay Time	1.6 2022		35	80	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		45	100	ns
Qg	Total Gate Charge	V _{DS} = -400 V, I _D = -2.7 A,		18	23	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		3.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		9.2		nC
Drain-S	Source Diode Characteristics at Maximum Continuous Drain-Source Dio	ode Forward Current			-2.1	А
	maximum r dissa si am socios si origina samoni				-8.4	Α
I _{SM}						
I _{SM} V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.1 \text{ A}$		-	-5.0	V
	Drain-Source Diode Forward Voltage Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = -2.1 \text{ A}$ $V_{GS} = 0 \text{ V, } I_S = -2.7 \text{ A,}$ $dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)		270	-5.0 	V ns

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 102mH, I_{AS} = -2.1A, V_{DD} = -50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq -2.7A, di/dt \leq 200 Δ /μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300 μ s, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

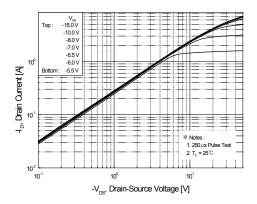


Figure 1. On-Region Characteristics

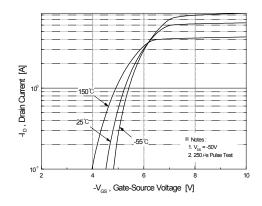


Figure 2. Transfer Characteristics

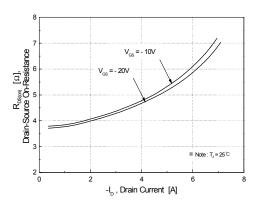


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

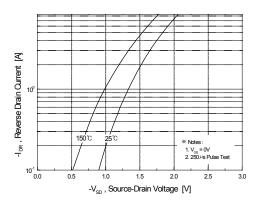


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

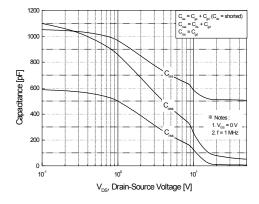


Figure 5. Capacitance Characteristics

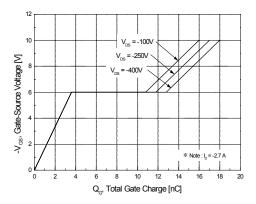
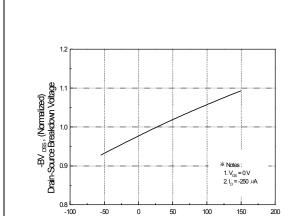


Figure 6. Gate Charge Characteristics



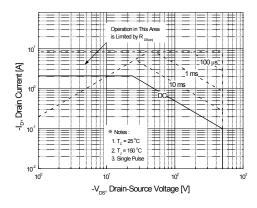
Typical Characteristics (Continued)

2.5 (Nonline 1.10 (Nonline 1.1

Figure 7. Breakdown Voltage Variation vs. Temperature

 T_J , Junction Temperature [°C]

Figure 8. On-Resistance Variation vs. Temperature



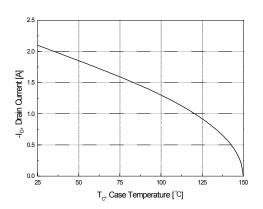


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

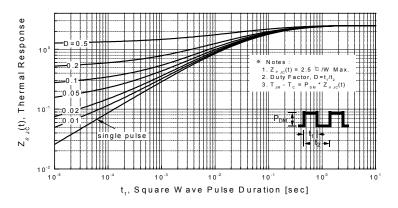
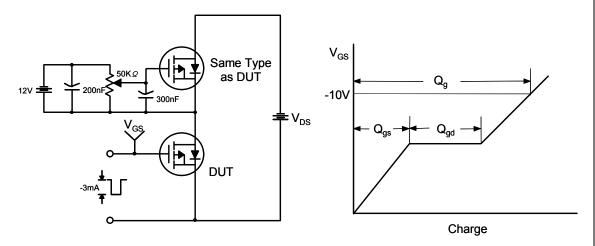
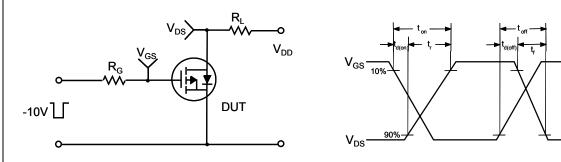


Figure 11. Transient Thermal Response Curve

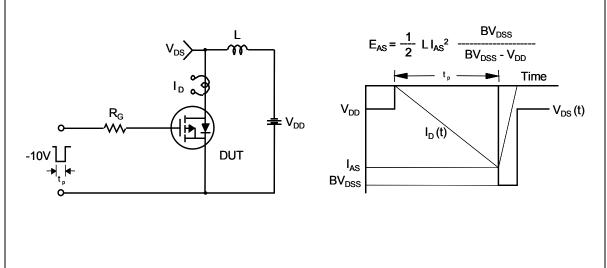
Gate Charge Test Circuit & Waveform



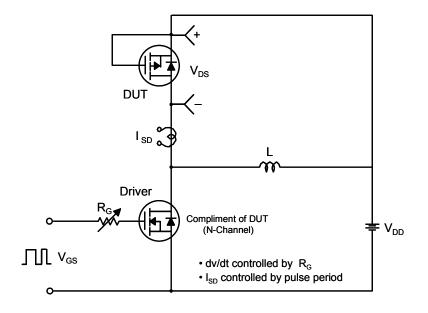
Resistive Switching Test Circuit & Waveforms

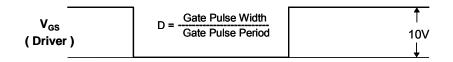


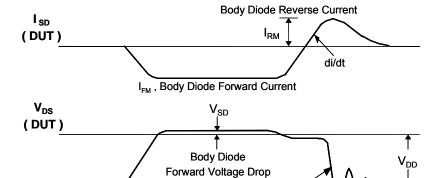
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms





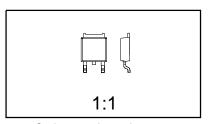


Body Diode Recovery dv/dt

Mechanical Dimensions

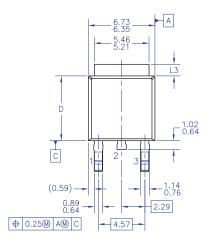
TO-252 (DPAK) (FS PKG Code 36)



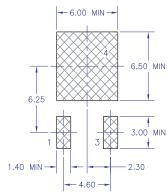


Scale 1:1 on letter size paper Dimensions shown below are in: millimeters

Part Weight per unit (gram): 0.33



SEE NOTE D



SEE DETAIL A

LAND PATTERN RECOMMENDATION

- 0.58 0.46

10.41 9.40

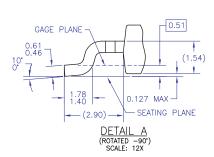




△ 0.10 B

- ALL DIMENSIONS ARE IN MILLIMETERS.
 THIS PACKAGE CONFORMS TO JEDEC, TO-252,
 ISSUE C, VARIATION AA & AB, DATED NOV. 1999.
- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M-1994.
 HEAT SINK TOP EDGE COULD BE IN CHAMFERED
 CORNERS OR EDGE PROTRUSION.
 DIMENSIONS L3,D,E1&D1 TABLE:

DIMETROTOTTO EGYDYETOOD T II						
	OPTION AA	OPTION AB				
L3	0.89-1.27	1.52-2.03				
D	5.97-6.22	5.33-5.59				
E1	4.32 MIN	3.81 MIN				
D1	5.21 MIN	4.57 MIN				







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